

1. General description

Hyperfast power diode in a 2-lead TO220F plastic package.



2. Features and benefits

- Fast switching
- Isolated plastic package
- Low leakage current
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses in associated MOSFET or IGBT

3. Applications

- Active PFC in air conditioner
- High frequency switched-mode power supplies
- Continuous Current Mode (CCM) Power Factor Correction (PFC)

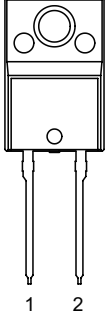
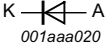
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V_{RRM}	repetitive peak reverse voltage			650			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; Fig. 1 ; Fig. 2		10			A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25 \mu s$; square-wave pulse		20			A
I_{FSM}	non-repetitive peak forward current	$t_p = 10 \text{ ms}$; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$; sine-wave pulse; Fig. 3		135			A
		$t_p = 8.3 \text{ ms}$; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$; sine-wave pulse		148			A
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	$I_F = 10 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 5		-	2.40	3.20	V
		$I_F = 10 \text{ A}$; $T_j = 150 \text{ }^\circ\text{C}$; Fig. 5		-	1.50	2.30	V
Dynamic characteristics							
t_{rr}	reverse recovery time	$I_F = 1 \text{ A}$; $V_R = 30 \text{ V}$; $di_F/dt = 200 \text{ A}/\mu s$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 6		-	13	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	n.c.	mounting base; isolated		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYC10MX-650P	TO220F-2L	BYC10MX-650PQ	Tube	50	TO220Fd-2L	02-Aug-2022

7. Marking

Table 4. Marking codes

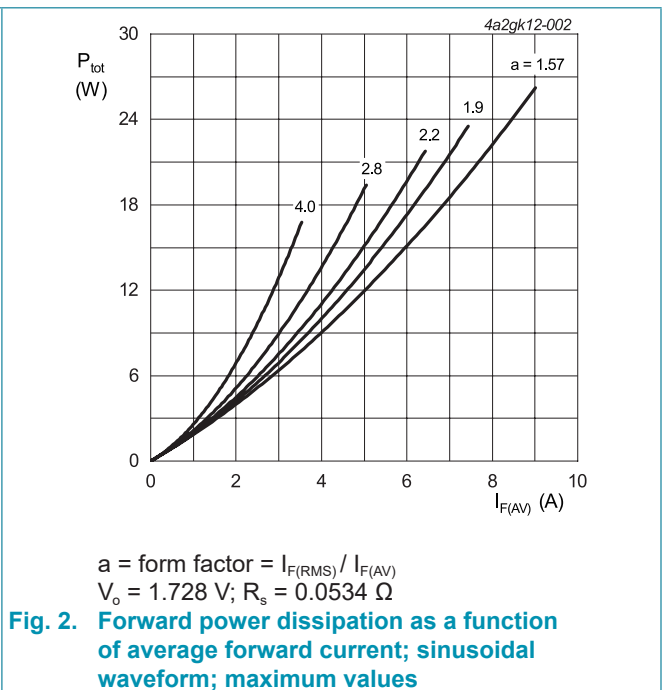
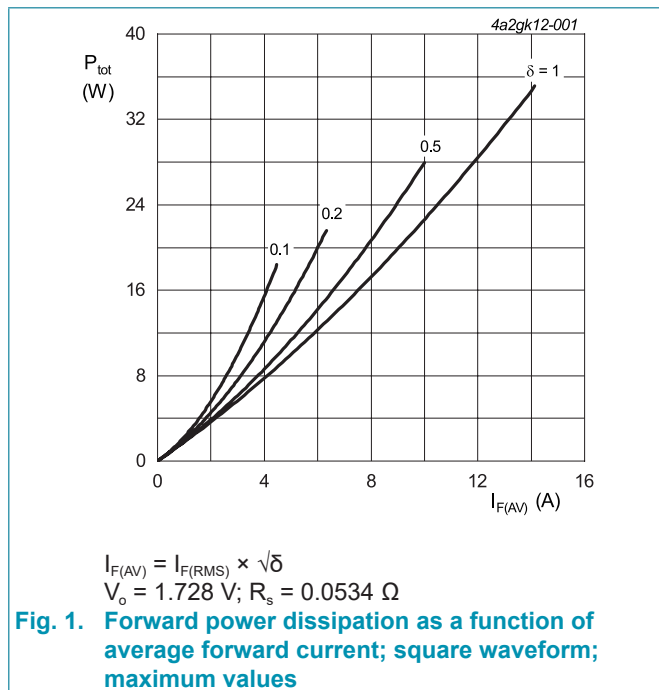
Type number	Marking codes
BYC10MX-650P	BYC10MX 650P

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			650	V
V_{RWM}	crest working reverse voltage			650	V
V_R	reverse voltage	DC		650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; Fig. 1 ; Fig. 2		10	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25 \mu s$; square-wave pulse		20	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10 ms$; $T_{j(init)} = 25 \text{ }^\circ C$; sine-wave pulse; Fig. 3		135	A
		$t_p = 8.3 ms$; $T_{j(init)} = 25 \text{ }^\circ C$; sine-wave pulse		148	A
T_{stg}	storage temperature			-65 to 175	$^\circ C$
T_j	junction temperature			-65 to 175	$^\circ C$



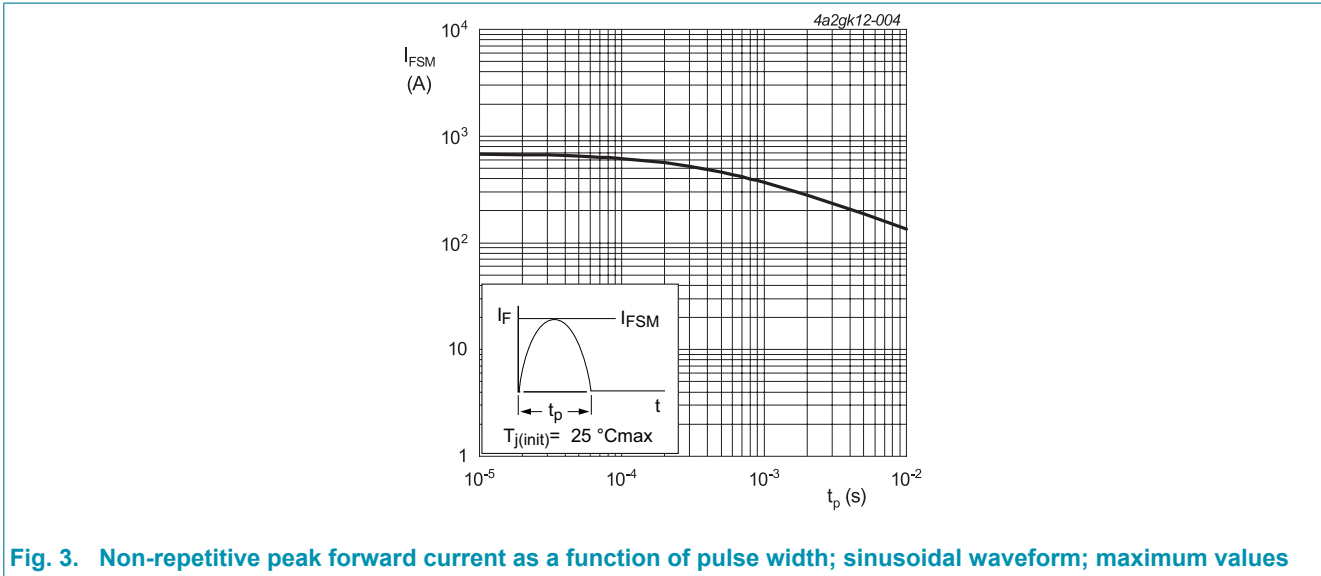


Fig. 3. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to heatsink	with heatsink compound; Fig 4		-	-	4.8	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

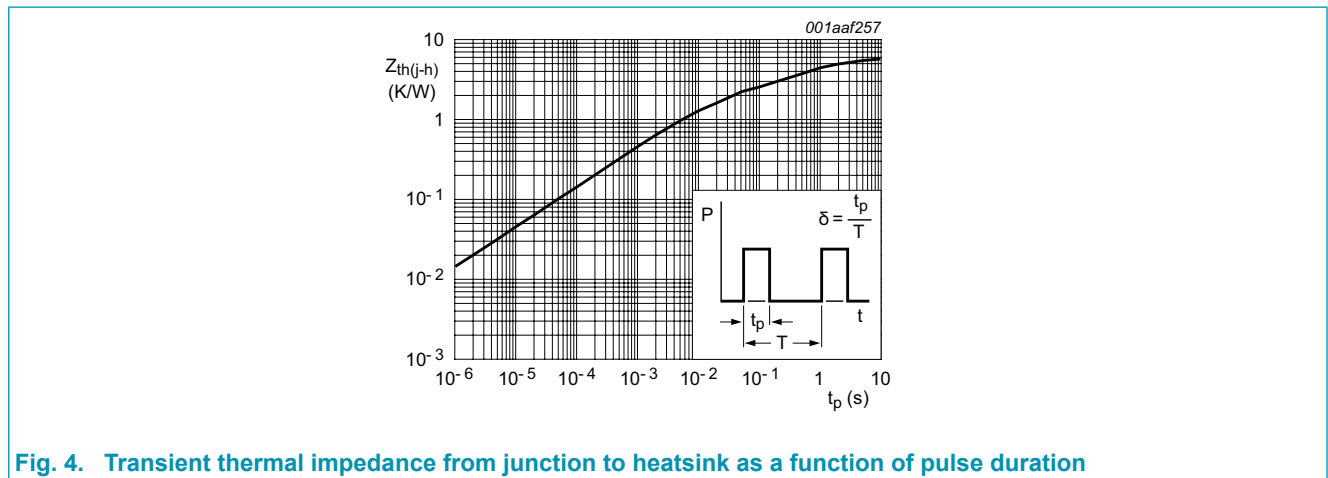


Fig. 4. Transient thermal impedance from junction to heatsink as a function of pulse duration

10. Isolation characteristics

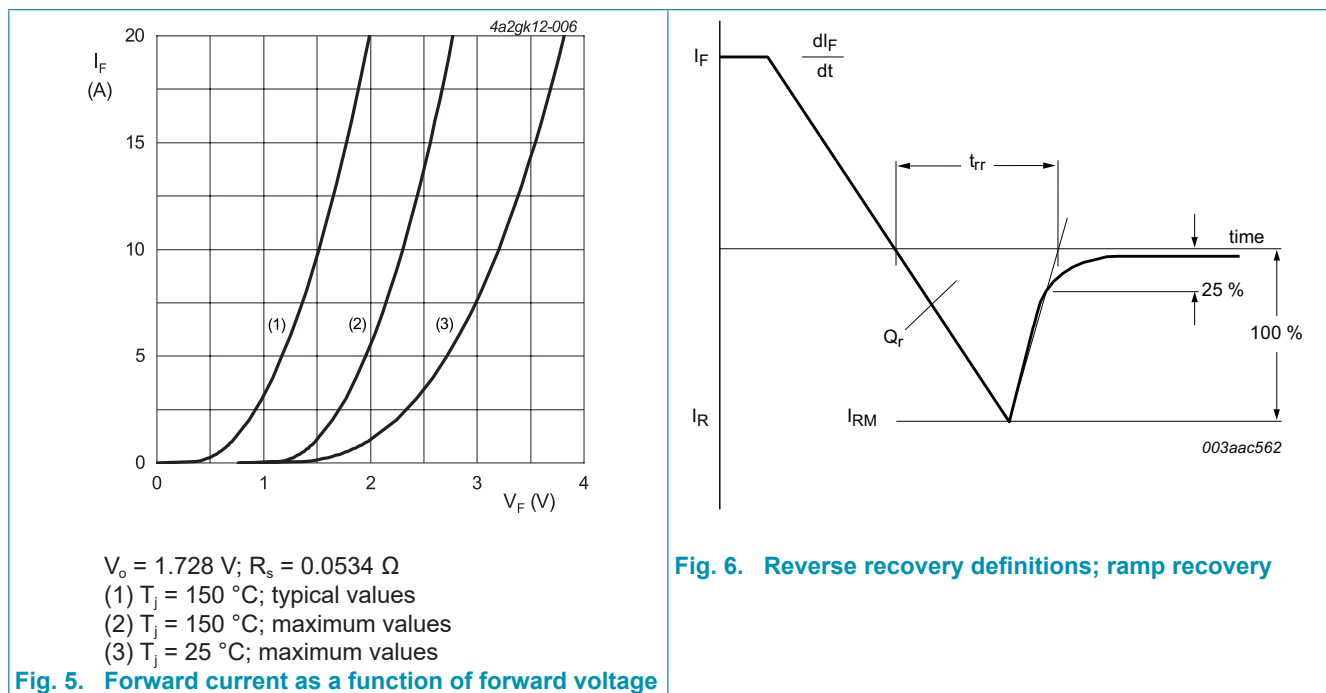
Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	50 Hz \leq f \leq 60 Hz; RH \leq 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
C_{isol}	isolation capacitance	f = 1 MHz; from cathode to external heatsink	-	10	-	pF

11. Characteristics

Table 8. Characteristics

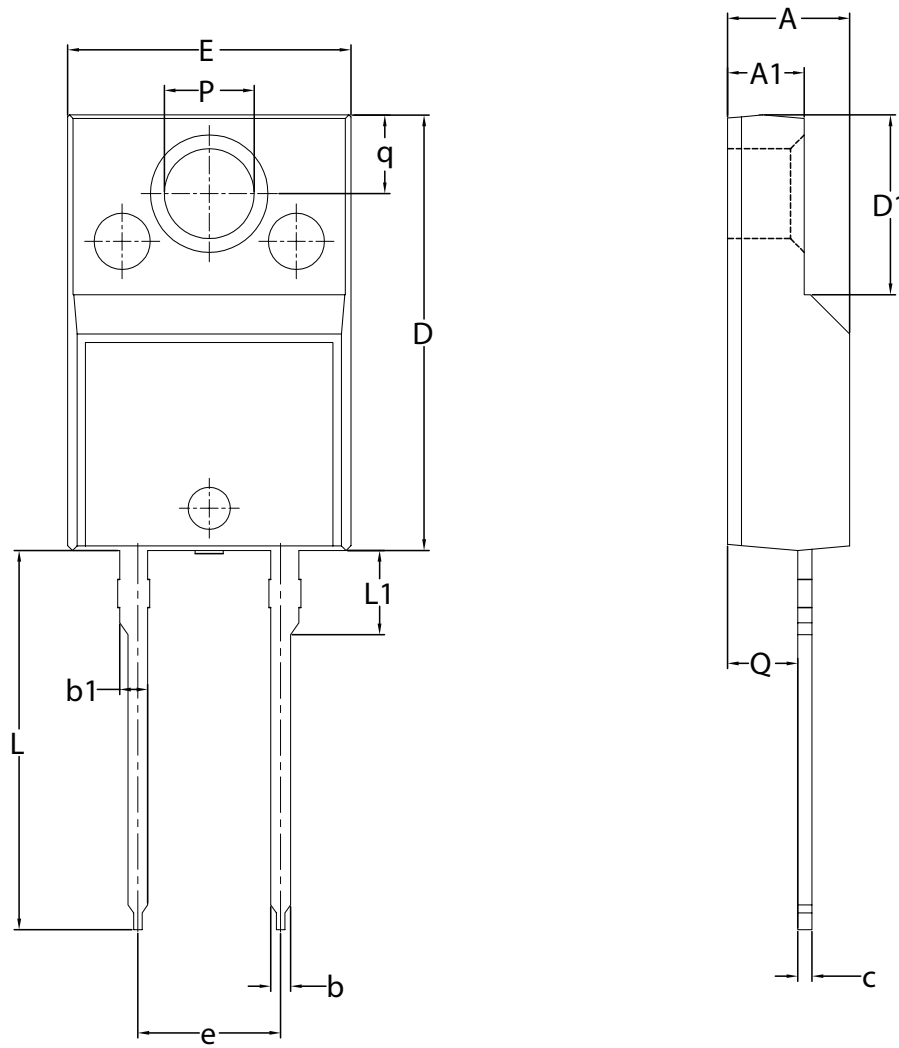
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	$I_F = 10 \text{ A}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 5}$		-	2.40	3.20	V
		$I_F = 10 \text{ A}; T_j = 150 \text{ }^\circ\text{C}; \text{ Fig. 5}$		-	1.50	2.30	V
I_R	reverse current	$V_R = 650 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$		-	0.5	30	μA
		$V_R = 650 \text{ V}; T_j = 150 \text{ }^\circ\text{C}$		-	0.1	0.8	mA
Dynamic characteristics							
Q_r	reverse charge	$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 7}$		-	37	-	nC
		$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{ Fig. 7}$		-	115	-	nC
t_{rr}	reverse recovery time	$I_F = 0.5 \text{ A}; I_R = 1 \text{ A}; I_{rr} = 0.25 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$		-	20	-	ns
		$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 7}$		-	13	-	ns
		$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 7}$		-	29	-	ns
		$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{ Fig. 7}$		-	48	-	ns
I_{RM}	peak reverse recovery current	$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 7}$		-	2.6	-	A
		$I_F = 10 \text{ A}; V_R = 200 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{ Fig. 7}$		-	4.8	-	A
E_{as}	non-repetitive avalanche energy	$T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$		10.8	-	-	mJ



12. Package outline

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 2 leads TO-220 'full pack'

TO220F-2L



Unit	A	A1	b	b1	c	D	D1	E	e	L	L1	P	Q	q
min	4.00	2.50	0.70	0.90	0.40	15.20	6.30	9.80	5.08 (BSC)	13.50	2.80	3.00	2.30	2.60
max	4.60	3.10	0.90	1.10	0.70	15.80	6.50	10.30		14.40	3.30	3.40	2.80	3.00

Note:

1. All dimensions don't include mold flash and metal protrusion.

13. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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